

SWITCHMODE Power Rectifier

MUR220

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 25 Nanosecond Recovery Times
- 175 °C Operating Junction Temperature
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- These are Pb-Free Devices*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260 °C Max. for 10 Seconds
- Polarity: Cathode Indicated by Polarity Band

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	200 –	V
Average Rectified Forward Current (Note 2) (Square Wave Mounting Method #3 Per Note 4)	$I_{F(AV)}$	2.0 @ $T_A = 90\text{ }^{\circ}\text{C}$	A
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I_{FSM}	35	A
Operating Junction Temperature and Storage Temperature Range	T_J, T_{stg}	– 65 to +175	°C

THERMAL CHARACTERISTICS

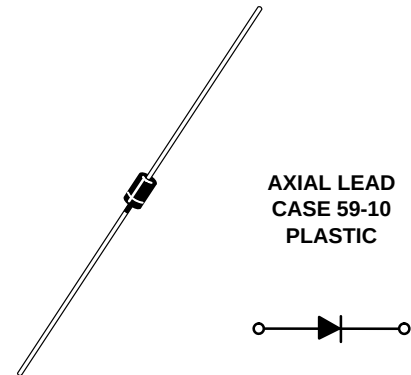
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	(Note 4)	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle $\leq$ 2.0%.

* For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDDRRM/D](#).

ULTRAFAST RECTIFIER 2.0 AMPERES – 200 VOLTS



MARKING DIAGRAM



A = Assembly Location
MUR220 = Device Code
YY = Year
WW = Work Week
■ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MUR220G	Axial Lead**	1000 Units / Bulk
MUR220RLG	Axial Lead**	5000 / Tape & Reel

DISCONTINUED (Note 1)

MUR220	Axial Lead**	1000 Units / Bulk
MUR220RL	Axial Lead**	5000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

** This package is inherently Pb-Free.

1. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on [www.onsemi.com](#).

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 2.0$ Amp, $T_J = 150$ °C) ($I_F = 2.0$ Amp, $T_J = 25$ °C)	V_F	0.75 0.95	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 150$ °C) (Rated dc Voltage, $T_J = 25$ °C)	I_R	50 2.0	μ A
Maximum Reverse Recovery Time ($I_F = 1.0$ Amp, $di/dt = 50$ Amp/ μ s) ($I_F = 0.5$ Amp, $I_R = 1.0$ Amp, $I_{REC} = 0.25$ A)	t_{rr}	35 25	ns
Maximum Forward Recovery Time ($I_F = 1.0$ A, $di/dt = 100$ A/ μ s, I_{REC} to 1.0 V)	t_{fr}	25	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle $\leq$ 2.0%.

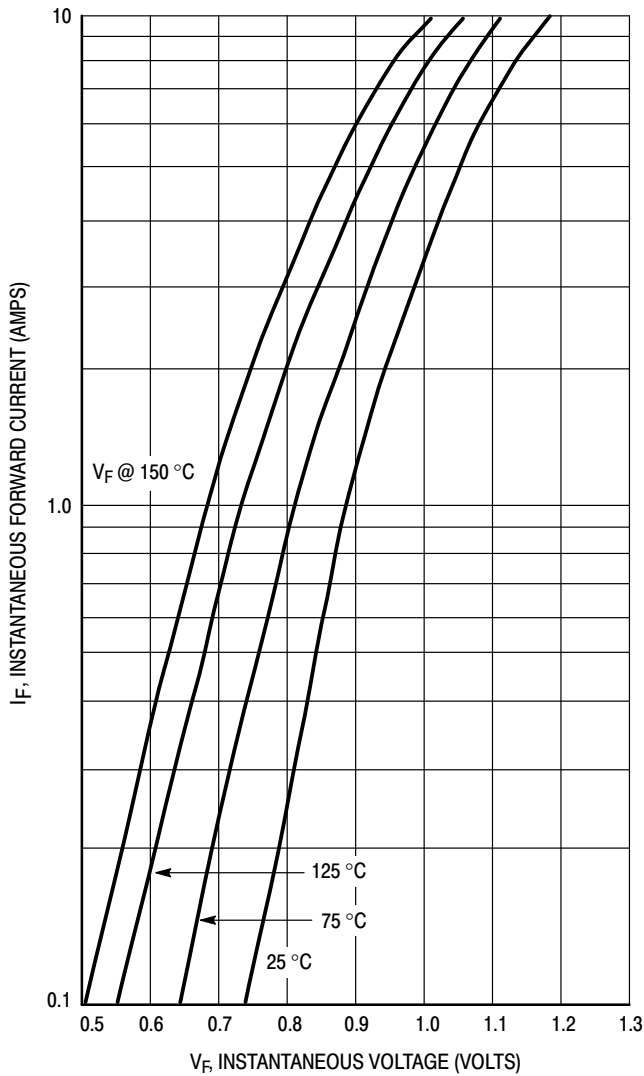


Figure 1. Maximum Forward Voltage

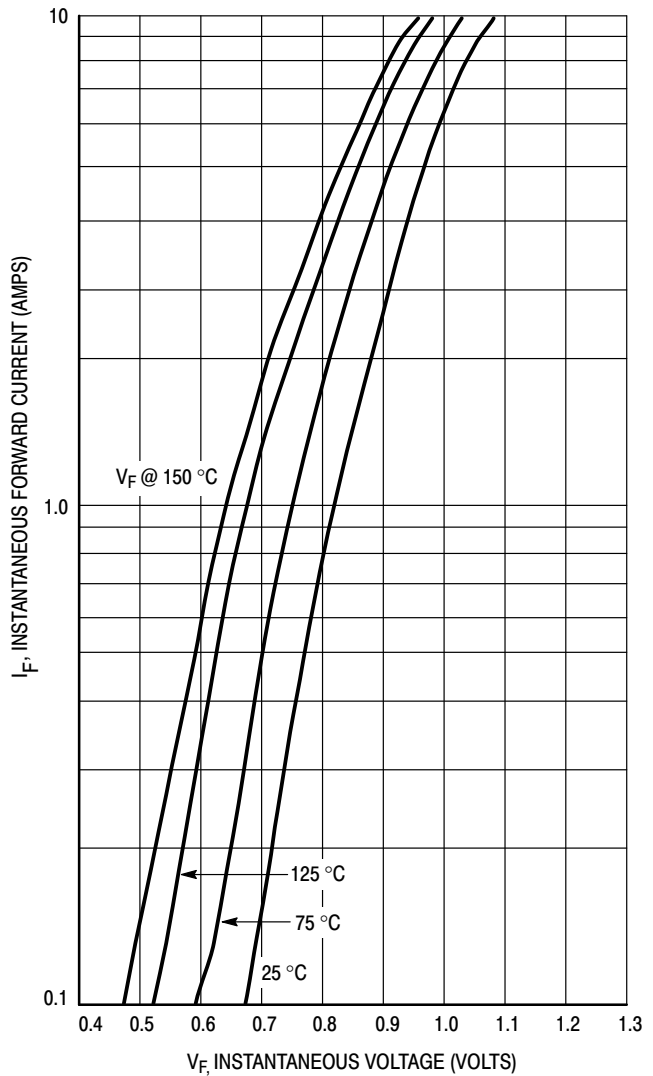


Figure 2. Typical Forward Voltage

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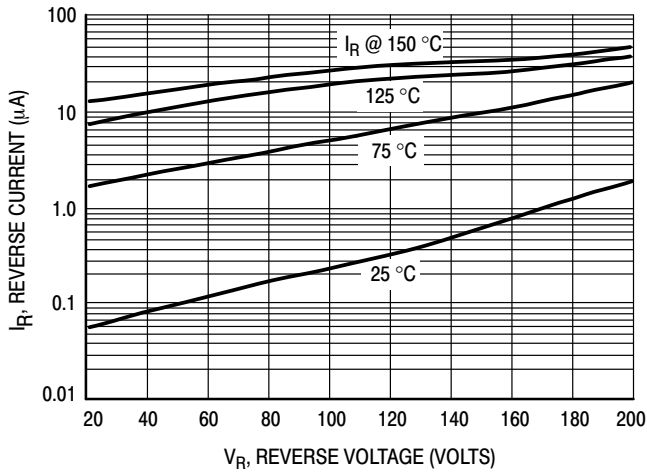


Figure 3. Maximum Reverse Current

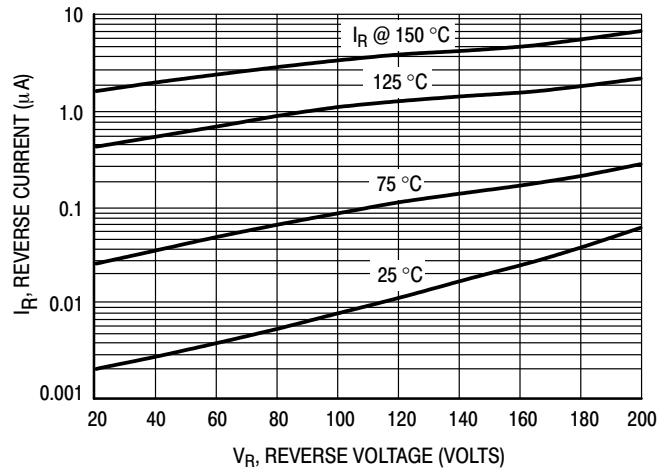


Figure 4. Typical Reverse Current

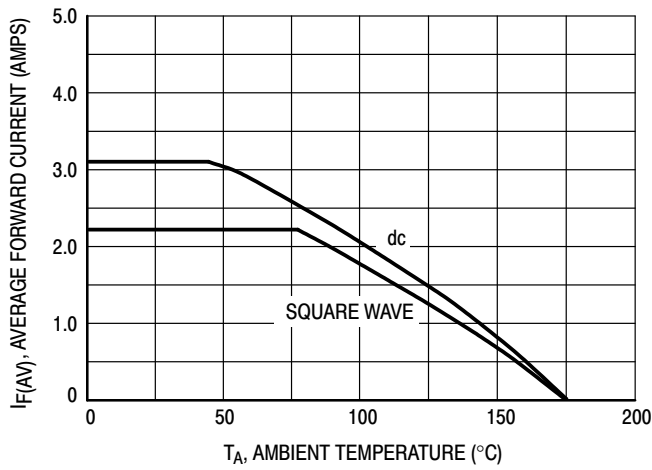


Figure 5. Current Derating

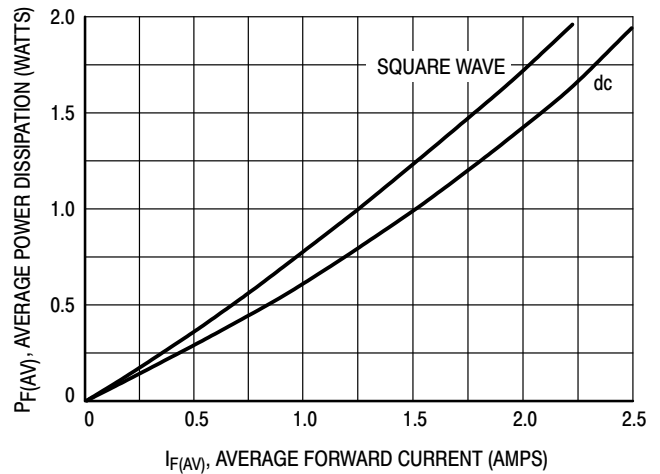


Figure 6. Power Dissipation

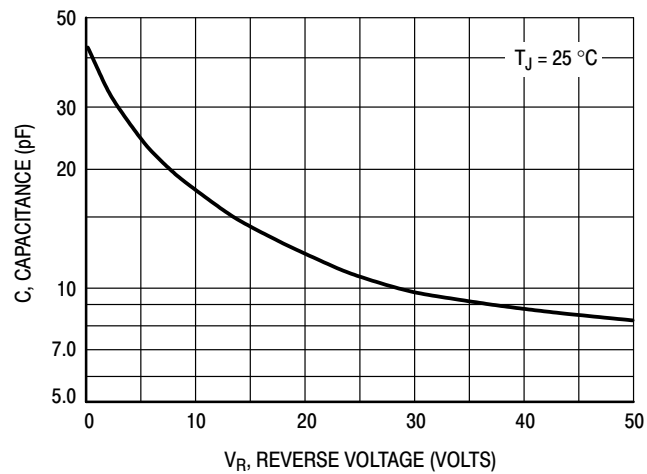


Figure 7. Typical Capacitance

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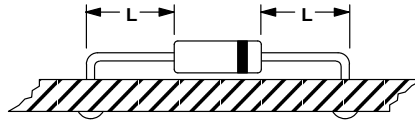
NOTE 4. – AMBIENT MOUNTING DATA

Data shown for Thermal Resistance, Junction-to-Ambient ($R_{\theta JA}$) for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

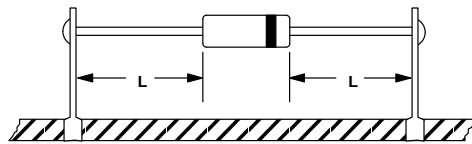
TYPICAL VALUES FOR $R_{\theta JA}$ IN STILL AIR

Mounting Method		Lead Length, L			Units
		1/8	1/4	1/2	
1	$R_{\theta JA}$	52	65	72	°C/W
2		67	80	87	°C/W
3		50			°C/W

MOUNTING METHOD 1

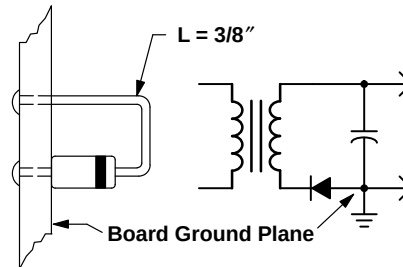


MOUNTING METHOD 2



Vector Pin Mounting

MOUNTING METHOD 3



P.C. Board with
1-1/2" X 1-1/2" Copper Surface

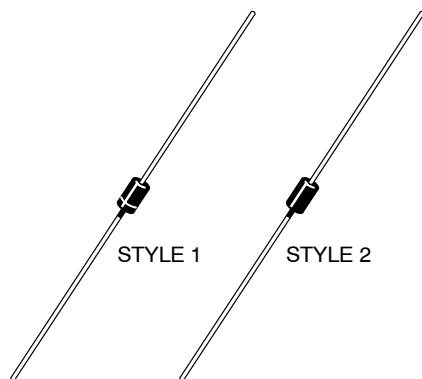
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REVISION HISTORY

Revision	Description of Changes	Date
8	Rebranded the Data Sheet to onsemi format. MUR220, MUR220RL OPN marked as Discontinued.	10/9/2025

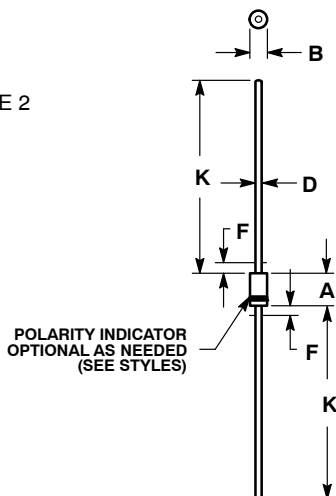
This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.





AXIAL LEAD
CASE 59-10
ISSUE U

DATE 15 FEB 2005

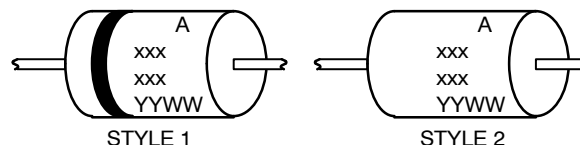


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ALL RULES AND NOTES ASSOCIATED WITH JEDEC DO-41 OUTLINE SHALL APPLY.
4. POLARITY DENOTED BY CATHODE BAND.
5. LEAD DIAMETER NOT CONTROLLED WITHIN F DIMENSION.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.161	0.205	4.10	5.20
B	0.079	0.106	2.00	2.70
D	0.028	0.034	0.71	0.86
F	---	0.050	---	1.27
K	1.000	---	25.40	---

GENERIC
MARKING DIAGRAM*



xxx = Specific Device Code
A = Assembly Location
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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